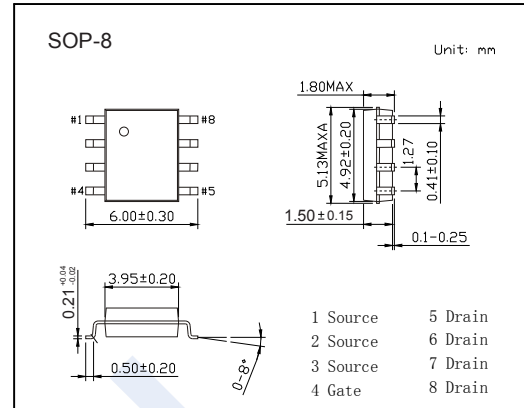
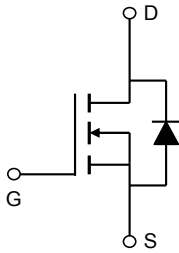


N-Channel MOSFET

AO4448 (KO4448)

■ Features

- $V_{DS} (V) = 80V$
- $I_D = 10 A (V_{GS} = 10V)$
- $R_{DS(ON)} < 16m\Omega (V_{GS} = 10V)$
- $R_{DS(ON)} < 20m\Omega (V_{GS} = 7V)$



■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	V_{DS}	80	V	
Gate-Source Voltage	V_{GS}	± 25		
Continuous Drain Current	I_D	$T_A=25^\circ C$	10	
		$T_A=70^\circ C$	8	
Pulsed Drain Current	I_{DM}	70	A	
Avalanche Current	I_{AS}, I_{AR}	45		
Avalanche Energy	$L=0.1mH$	E_{AS}, E_{AR}	101	mJ
Power Dissipation	P_D	$T_A=25^\circ C$	3.1	W
		$T_A=70^\circ C$	2	
Thermal Resistance.Junction- to-Ambient	R_{thJA}	$t \leq 10s$	40	$^\circ C/W$
		Steady-State	75	
Thermal Resistance.Junction- to-Lead	R_{thJL}	24		
Junction Temperature	T_J	150	$^\circ C$	
Storage Temperature Range	T_{stg}	-55 to 150		

N-Channel MOSFET

AO4448 (KO4448)

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V _{bss}	I _D =250μA, V _{GS} =0V	80			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V			10	μA
		V _{DS} =80V, V _{GS} =0V, T _J =55°C			50	
Gate-Body Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±25V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.8		4.2	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =10A			16	mΩ
		V _{GS} =10V, I _D =10A, T _J =125°C			28.5	
		V _{GS} =7V, I _D =8A			20	
On State Drain Current	I _{D(on)}	V _{GS} =10V, V _{DS} =5V	70			A
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =10A		23		S
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =40V, f=1MHz	1335		2005	pF
Output Capacitance	C _{oss}		150		280	
Reverse Transfer Capacitance	C _{rss}		40		100	
Gate Resistance	R _g		0.35		1.2	
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =40V, I _D =10A	22		34	nC
Gate Source Charge	Q _{gs}		8.8		13	
Gate Drain Charge	Q _{gd}		5		11	
Turn-On DelayTime	t _{d(on)}	V _{GS} =10V, V _{DS} =40V, R _L =4Ω, R _{GEN} =3Ω		12		ns
Turn-On Rise Time	t _r			9		
Turn-Off DelayTime	t _{d(off)}			20		
Turn-Off Fall Time	t _f			8		
Body Diode Reverse Recovery Time	t _{rr}	I _F = 10A, di/dt= 500A/μs	14.5		27.5	nC
Body Diode Reverse Recovery Charge	Q _{rr}		45.5		85	
Maximum Body-Diode Continuous Current	I _S				4	A
Diode Forward Voltage	V _{SD}	I _S =1A, V _{GS} =0V			1	V

Note : The static characteristics in Figures 1 to 6 are obtained using <300us pulses, duty cycle 0.5% max.

■ Marking

Marking	4448 KC****
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N-Channel MOSFET AO4448 (KO4448)

■ Typical Characteristics

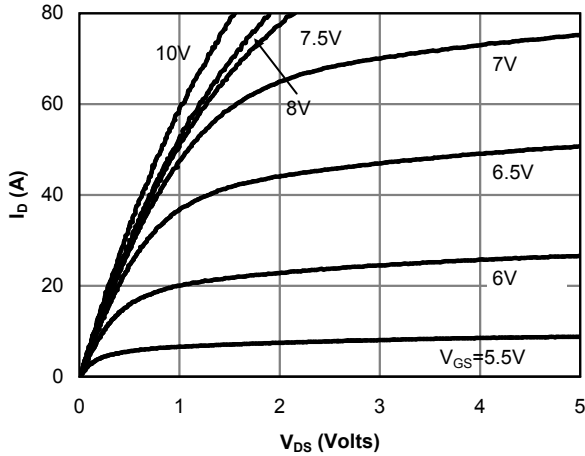


Fig 1: On-Region Characteristics (Note E)

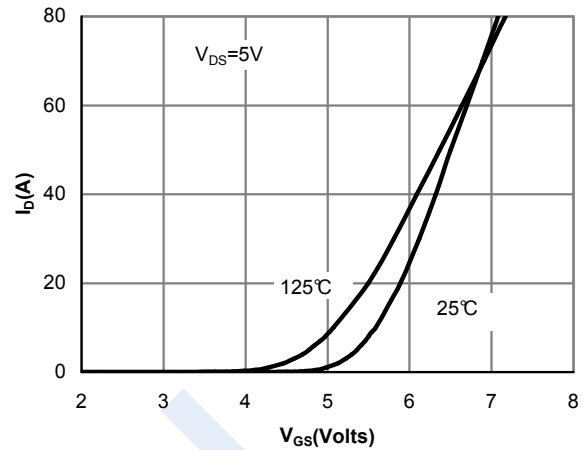


Figure 2: Transfer Characteristics (Note E)

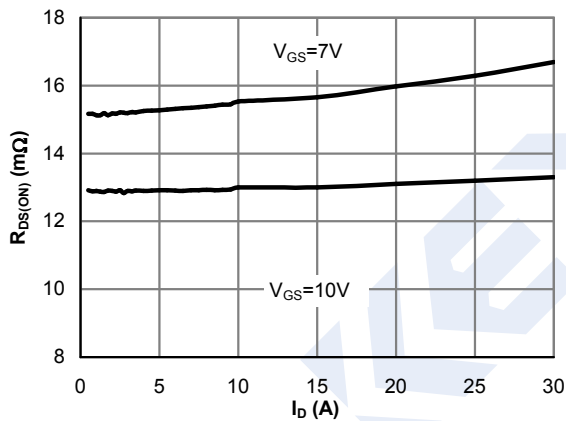


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

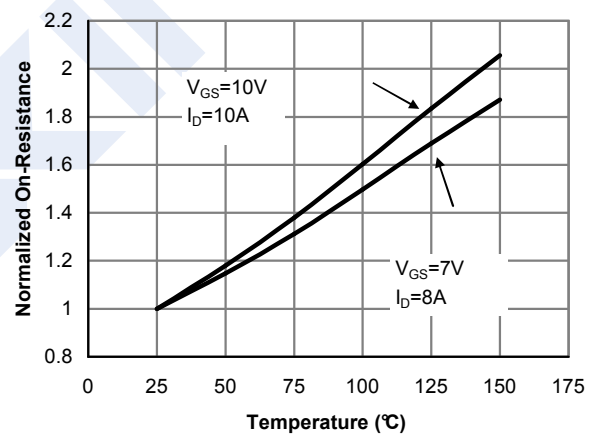


Figure 4: On-Resistance vs. Junction Temperature (Note E)

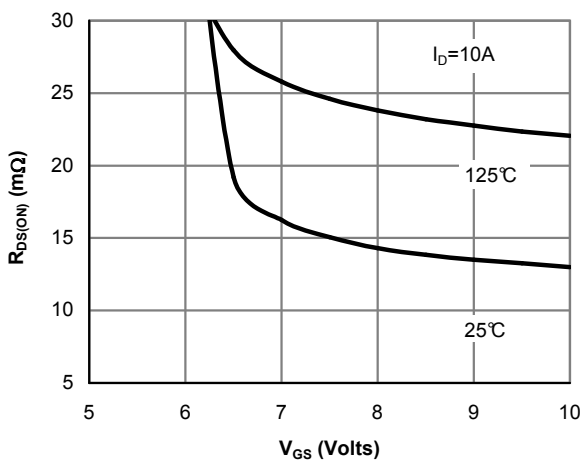


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

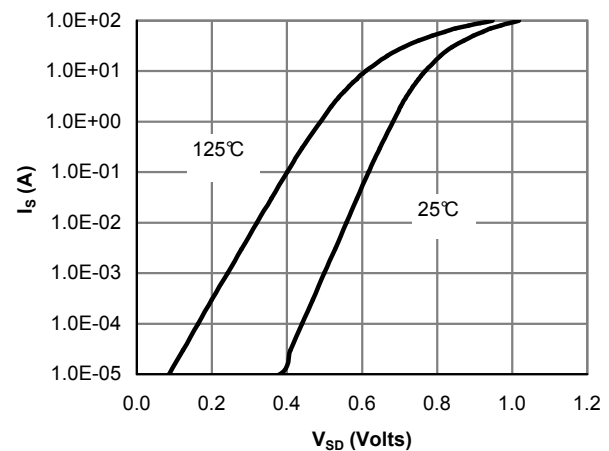


Figure 6: Body-Diode Characteristics (Note E)

N-Channel MOSFET AO4448 (KO4448)

■ Typical Characteristics

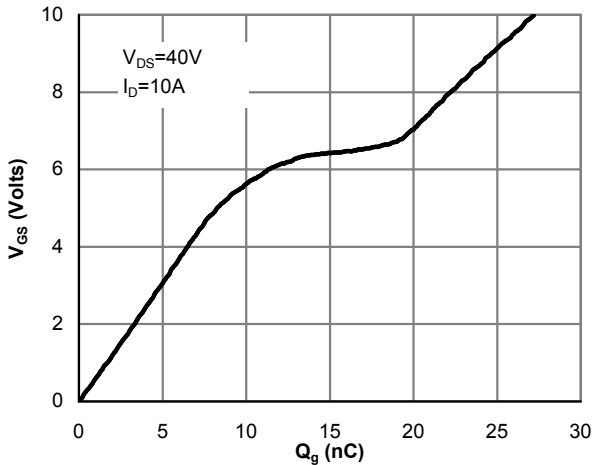


Figure 7: Gate-Charge Characteristics

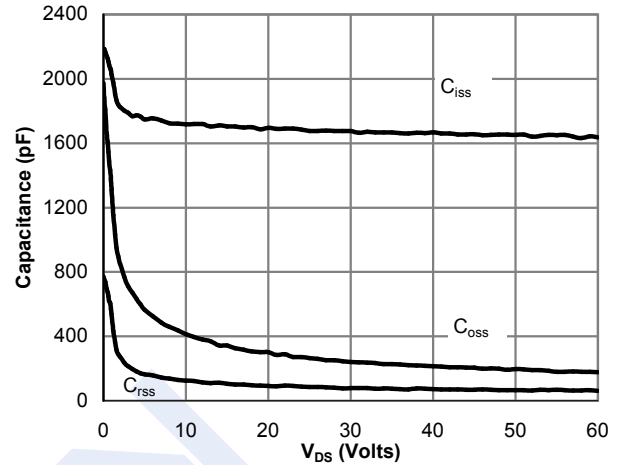


Figure 8: Capacitance Characteristics

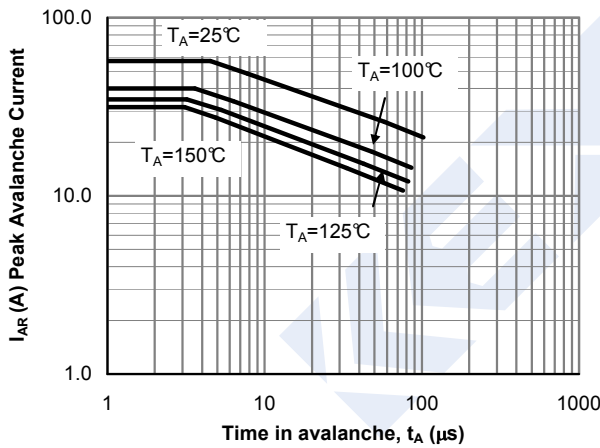


Figure 9: Single Pulse Avalanche capability (Note C)

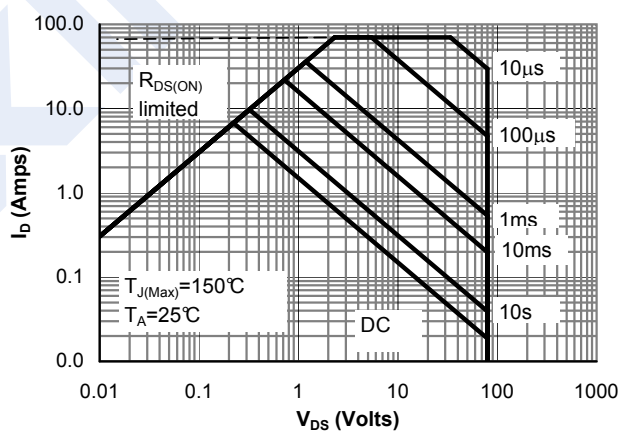


Figure 10: Maximum Forward Biased Safe Operating Area (Note F)

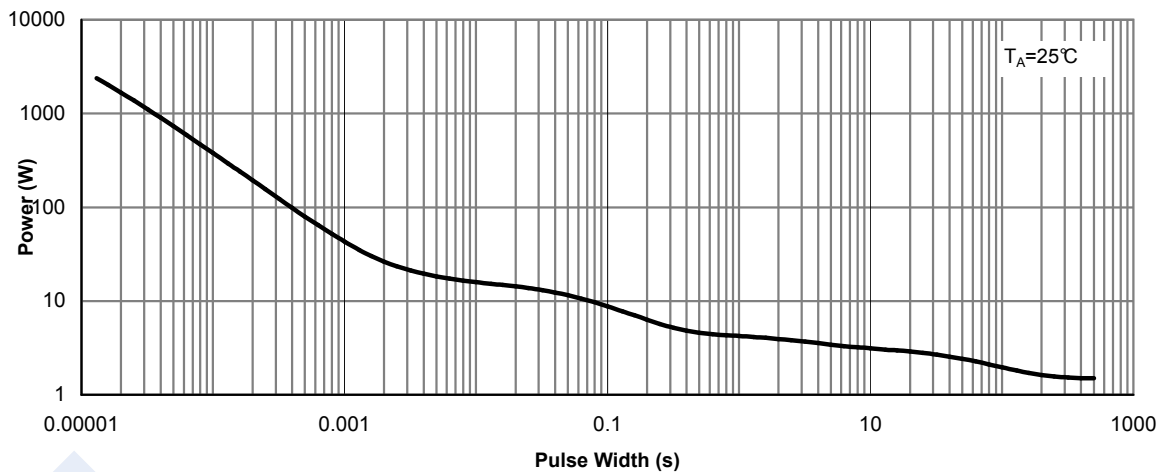


Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)

N-Channel MOSFET AO4448 (KO4448)

■ Typical Characteristics

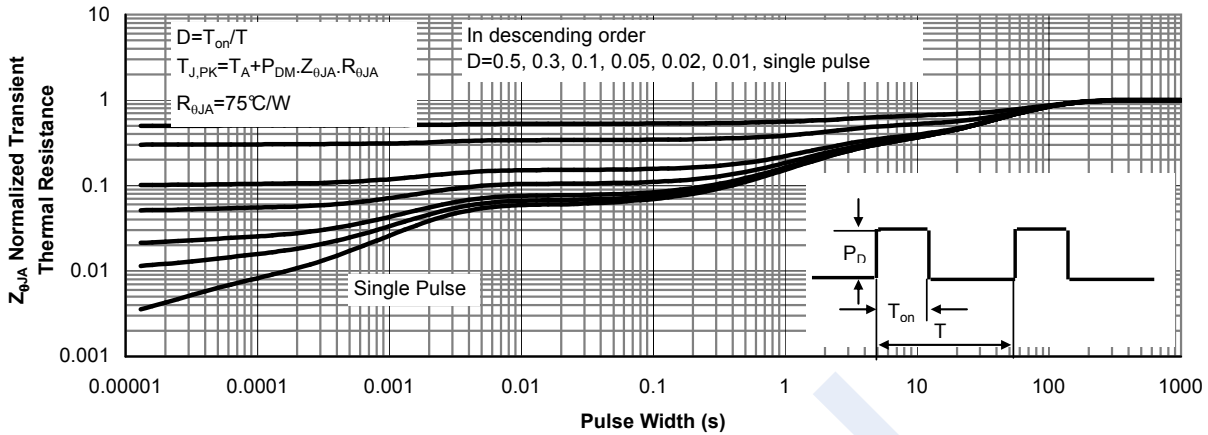


Figure 12: Normalized Maximum Transient Thermal Impedance (Note F)

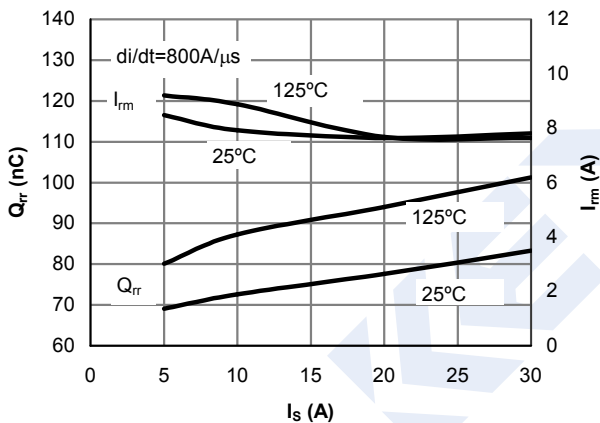


Figure 13: Diode Reverse Recovery Charge and Peak Current vs. Conduction Current

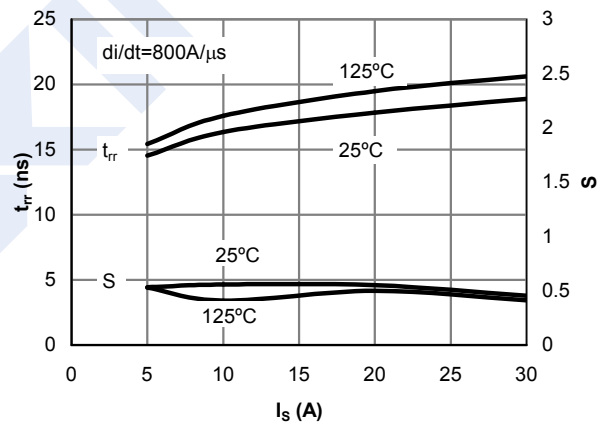


Figure 14: Diode Reverse Recovery Time and Softness Factor vs. Conduction Current

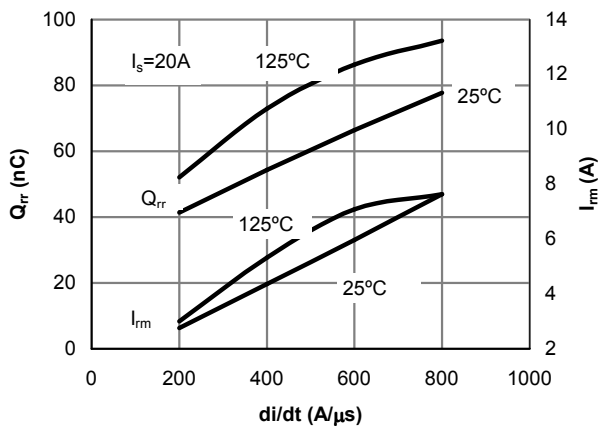


Figure 15: Diode Reverse Recovery Charge and Peak Current vs. di/dt

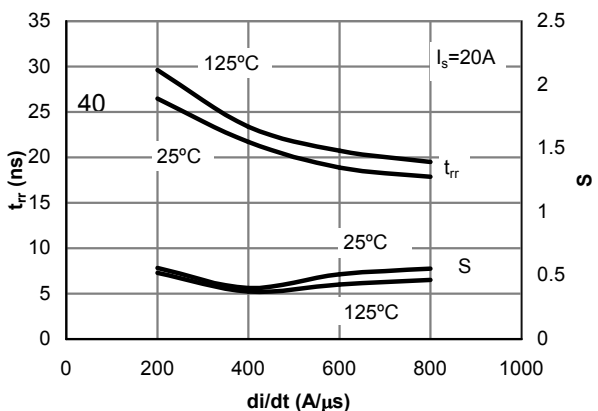


Figure 16: Diode Reverse Recovery Time and Softness Factor vs. di/dt